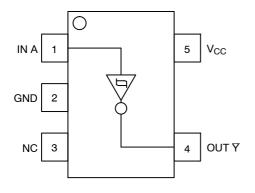
Single Schmitt-Trigger Inverter

The NL17SH14 is a single gate CMOS Schmitt-trigger inverter fabricated with silicon gate CMOS technology. The internal circuit is composed of three stages, including a buffer output which provides high noise immunity and stable output. The NL17SH14 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage. This allows the NL17SH14 to be used to interface 5 V circuits to 3 V circuits.

The NL17SH14 can be used to enhance noise immunity or to square up slowly changing waveforms.

Features

- High Speed: $t_{PD} = 4.0 \text{ ns} (Typ) \text{ at } V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1.0 \ \mu A$ (Max) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 101
- These Devices are Pb-Free and are RoHS Compliant



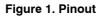




Figure 2. Logic Symbol



ON Semiconductor®

http://onsemi.com

MARKING DIAGRAM





R = Specific Device Code M = Month Code

PIN ASSIGNMENT							
1 IN A							
2	GND						
3	NC						
4	OUT Y						
5 V _{CC}							

FUNCTION TABLE

Input A	Output Y
L	Н
Н	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit		
V _{CC}	DC Supply Voltage	–0.5 to +7.0	V		
V _{IN}	DC Input Voltage		-0.5 to +7.0	V	
V _{OUT}	DC Output Voltage		–0.5 to V _{CC} + 0.5	V	
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA	
Ι _{ΟΚ}	DC Output Diode Current	utput Diode Current $V_{OUT} < GND, V_{OUT} > V_{CC}$			
I _{OUT}	DC Output Source/Sink Current	±12.5	mA		
I _{CC}	DC Supply Current per Supply Pin	±25	mA		
I _{GND}	DC Ground Current per Ground Pin	±25	mA		
T _{STG}	Storage Temperature Range	-65 to +150	°C		
ΤL	Lead Temperature, 1 mm from Case for 10 Second	S	260	°C	
TJ	Junction Temperature Under Bias		+150	°C	
MSL	Moisture Sensitivity		Level 1		
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in		
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>2000 >300 N/A	V	
ILATCHUP	Latchup Performance Above V _{CC}	and Below GND at 125°C (Note 5)	±100	mA	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

2. Tested to EIA/JESD22-A114-A.

3. Tested to EIA/JESD22-A115-A.

4. Tested to JESD22-C101-A.

5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit	
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V	
V _{IN}	Digital Input Voltage			5.5	V
V _{OUT}	Output Voltage			V _{CC}	V
T _A	A Operating Temperature Range			+125	°C
Δt / ΔV	Input Transition Rise or Fail Rate $ \begin{array}{c} V_{CC} = 3.3 \ V \pm 0.3 \ V \\ V_{CC} = 5.0 \ V \pm 0.5 \ V \end{array} $			No Limit No Limit	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

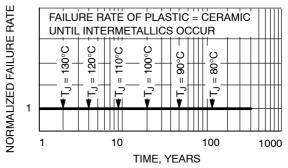


Figure 3. Failure Rate vs. Time Junction Temperature

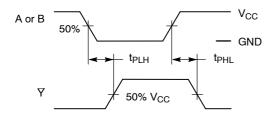
			v _{cc}	T _A = 25°C		T _A ≤	85°C	- 55°C 1	to 125°C		
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Мах	Unit
V _{T+}	Positive Threshold Voltage		3.0 4.5 5.5		2.0 3.0 3.6	2.2 3.15 3.85		2.2 3.15 3.85		2.2 3.15 3.85	V
V _{T-}	Negative Threshold Voltage		3.0 4.5 5.5	0.9 1.35 1.65	1.5 2.3 2.9		0.9 1.35 1.65		0.9 1.35 1.65		V
V _H	Hysteresis Voltage		3.0 4.5 5.5	0.3 0.4 0.5	0.57 0.67 0.74	1.2 1.4 1.6	0.3 0.4 0.5	1.2 1.4 1.6	0.3 0.4 0.5	1.2 1.4 1.6	V
V _{OH}	High-Level Output Voltage	$V_{IN} \leq V_{Tmin} \\ I_{OH} = -50 \ \mu A$	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} \leq V_{Tmin} \\ I_{OH} = -4 \text{ mA} \\ I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V _{OL}	Low-Level Output Voltage	$V_{IN} \ge V_{Tmax}$ $I_{OL} = 50 \ \mu A$	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} \ge V_{Tmax}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Input Leakage Current	$V_{IN} = 5.5 V \text{ or GND}$	0 to 5.5			±0.1		±1.0		±1.0	μA
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1.0		20		40	μA

DC ELECTRICAL CHARACTERISTICS

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

		V _{cc}	Test	T _A = 25°C		T _A ≤	85°C	- 55°C 1	to 125°C		
Symbol	Parameter	(V)	Conditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay, A to \overline{Y}	3.0 to 3.6	C _L = 15 pF C _L = 50 pF		7.0 8.5	12.8 16.3	1.0 1.0	15.0 18.5	1.0 1.0	17.0 20.5	ns
		4.5 to 5.5	C _L = 15 pF C _L = 50 pF		4.0 5.5	8.6 10.6	1.0 1.0	10.0 12.0	1.0 1.0	11.5 13.5	
C _{IN}	Input Capacitance				5.0	10		10		10	pF
Typical @ 25°C, V _{CC} = 5.0 V											
CPD	Power Dissipation Capaci	tance (Note 6)					7.0				pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



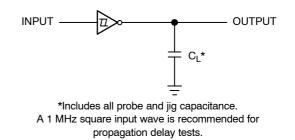


Figure 4. Switching Waveform

Figure 5. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NL17SH14P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



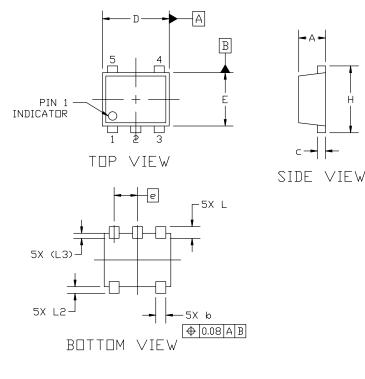


SOT-953 1.00x0.80x0.37, 0.35P CASE 527AE ISSUE F

DATE 17 JAN 2024

NDTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS DF THE BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.



GENERIC MARKING DIAGRAM*

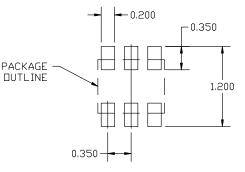


- X = Specific Device Code M = Month Code
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON26457D Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.					
DESCRIPTION:	SOT-953 1.00x0.80x0.37, 0	PAGE 1 OF 1				

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights of others.

MILLIMETERS								
DIM	MIN	NDM	MAX					
A	0.34	0.37	0,40					
b	0.10	0.15	0.20					
С	0.07	0.12	0.17					
D	0,95	1,00	1.05					
E	0,75	0,80	0.85					
e	(D.35 BSC)					
Н	0,95	1.00	1.05					
Ĺ	0.125	0.175	0.225					
L2	0.05	0.10	0.15					
L3	0.075 (REF)							



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent_Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com

ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at <u>www.onsemi.com/support/sales</u>